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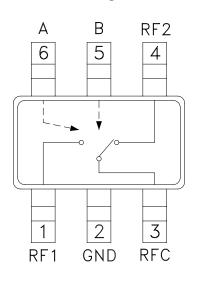


Typical Applications

The HMC197A(E) is ideal for:

- MMDS & WirelessLAN
- PCMCIA Wireless Cards
- Portable Wireless

Functional Diagram



Features

Low Insertion Loss: 0.4 dB Ultra Small Package: SOT26

Input IP3: +45 dBm

Positive Control: 0/+3V @ 3 µA

General Description

The HMC197A(E) is a low-cost SPDT switch in a 6-lead SOT26 plastic package for use in general switching applications which require very low insertion loss and very small size. The device can control signals from DC to 3 GHz and is especially suited for 900 MHz, 1.8 - 2.2 GHz, and 2.4 GHz ISM applications with less than 1 dB loss. The design provides exceptional insertion loss performance, ideal for filter and receiver switching. RF1 and RF2 are reflective shorts when "Off". The two control voltages require a minimal amount of DC current and offer compatibility with most CMOS & TTL logic families. See HMC221A(E) for same performance in an alternate SOT26 pin-out.

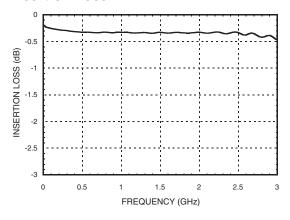
Electrical Specifications, $T_A = +25^{\circ}$ C, Vctl = 0/+3 to +8 Vdc, 50 Ohm System

Parameter	Frequency	Min.	Тур.	Max.	Units
Insertion Loss	DC - 1.0 GHz DC - 2.0 GHz DC - 2.5 GHz DC - 3.0 GHz		0.4 0.45 0.7 0.8	0.7 0.8 0.9 1.1	dB dB dB dB
Isolation	DC - 1.0 GHz DC - 2.0 GHz DC - 2.5 GHz DC - 3.0 GHz	24 24 18 14	28 28 22 18		dB dB dB dB
Return Loss	DC - 1.0 GHz DC - 2.0 GHz DC - 2.5 GHz DC - 3.0 GHz	20 16 14 10	30 22 17 13		dB dB dB dB
Input Power for 1dB Compression (Vctl = 0/+5V)	0.5 - 1.0 GHz 0.5 - 3.0 GHz	25 23	30 29		dBm dBm
Input Third Order Intercept (Vctl = 0/+5V) (Two-tone Input Power = +7 dBm Each Tone)	0.5 - 1.0 GHz 0.5 - 3.0 GHz	40 38	45 43		dBm dBm
Switching Characteristics	DC - 3.0 GHz				
tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)			3 10		ns ns

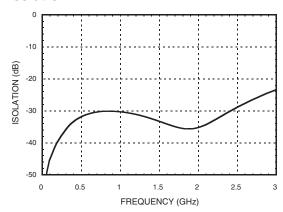




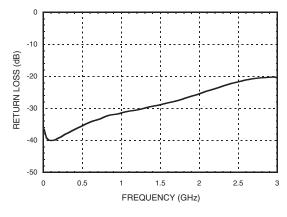
Insertion Loss



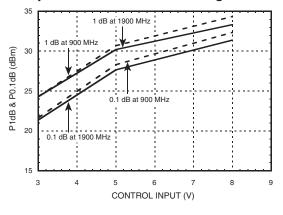
Isolation



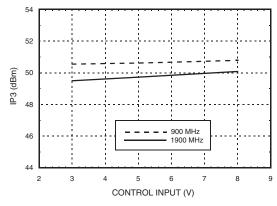
Return Loss



Input 0.1 and 1.0 dB
Compression vs. Control Voltage



Input Third Order Intercept Point vs. Control Voltage



Distortion vs. Control Voltage

Control Input	Third Order Intercept (dBm) +7 dBm Each Tone		
(Vdc)	900 MHz	1900 MHz	
+3	50	49	
+5	50	49	
+8	51	50	

Truth Table*Control Input Voltage Tolerances are ± 0.2 Vdc.

Contro	I Input*	Control	trol Current Signal Path Sta		ath State
A (Vdc)	B (Vdc)	la (μΑ)	lb (μΑ)	RF to RF1	RF to RF2
0	+3	-3	3	ON	OFF
+3	0	3	-3	OFF	ON
0	+5	-5	5	ON	OFF
+5	0	5	-5	OFF	ON
0	+8	-32	32	ON	OFF
+8	0	32	-32	OFF	ON





Compression vs. Control Voltage

	Carrier at 900 MHz		Carrier at 1900 MHz		
Control Input	Input Power for 0.1 dB Compression	Input Power for 1.0 dB Compression	Input Power for 0.1 dB Compression	Input Power for 1.0 dB Compression	
(Vdc)	(dBm)	(dBm)	(dBm)	(dBm)	
+3	21	24	21	24	
+5	28	30	27	30	
+8	32	34	31	33	

Caution: Do not operate in 1dB compression at power levels above $+31\,$ dBm (Vctl = $+5\,$ Vdc) and do not "hot switch" power levels greater than $+20\,$ dBm (Vctl = +5Vdc). DC blocks are required at ports RFC, RF1 and RF2.

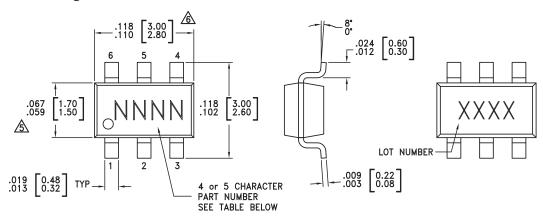
Absolute Maximum Ratings

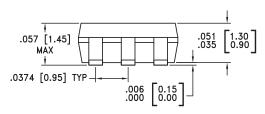
Control Voltage Range (A & B)	-0.2 to +12 Vdc	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	
ESD Sensitivity (HBM)	Class 1A	



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

Outline Drawing





NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC197A	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	197A XXXX
HMC197AE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	197AE XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX

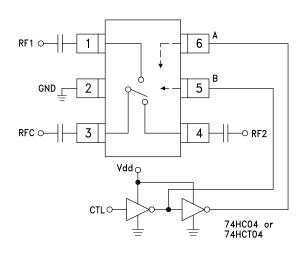




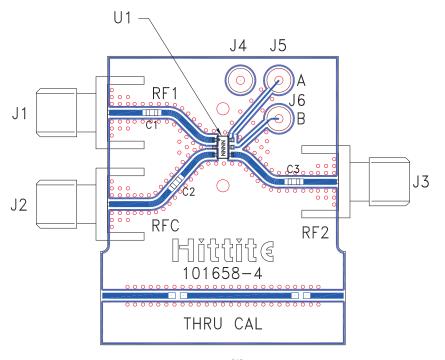
Typical Application Circuit

Notes:

- Set logic gate and switch Vdd = +3V to +5V and use HCT series logic to provide a TTL driver interface.
- Control inputs A/B can be driven directly with CMOS logic (HC) with Vdd of 5 to 8 Volts applied to the CMOS logic gates.
- 3. DC Blocking capacitors are required for each RF port as shown. Capacitor value determines lowest frequency of operation.
- Highest RF signal power capability is achieved with Vdd = +8V and A/B set to 0/+8V.



Evaluation Circuit Board



List of Materials for Evaluation PCB 101674 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
J4 - J6	DC Pin
C1 - C3	330 pF Capacitor, 0603 Pkg.
U1	HMC197A / HMC197AE SPDT Switch
PCB [2]	101658 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 Ohm impedance and the package ground leads and package bottom should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.